

REC

11-28-2000



SHEET

To the Honorable Commissioner of

101529144

attached original documents or copy thereof.

1. Name of conveying party(ies):

Won-Suk Yang
Yoo-Sang Hwang
Hong-Sik Jeong
Ki-Nam Kim

MUG
10-30-00

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):

Name: Samsung Electronics, Co., Ltd.

Internal Address: _____

Street Address: 416, Maetan-dong, Paldal-gu,
Suwon-city, Kyungki-do, Republic of Korea

City: _____ State _____ ZIP _____

Additional name(s) & address attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: October 26, 2000 and October 27, 2000

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: October 26 and 27, 2000

A. Patent Application No.(s)

B. Patent No.(s)

09/699591

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Anthony P. Onello, Jr.

Internal Address: Samuels, Gauthier & Stevens LLP

Street Address: 225 Franklin Street, Suite 3300

City: Boston State MA ZIP 02110

6. Total number of applications and registrations involved

1

7. Total fee (37 CFR 3.41)..... \$40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit Account Number:

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Anthony P. Onello, Jr.

Name of Person Signing

Anthony P. Onello, Jr.

Signature

October 30, 2000

Date

Total number of pages including cover sheet, attachments, and document

3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents and Trademarks, Box Assignments
Washington, D.C. 20231

ASSIGNMENT

We, Won-Sak Yoo of Poonglim APT 201-507, Dongchun-Ri, Sooji-Eup, Yongin-City, Kyungki-Do, Republic of Korea, Yoo-Sang Hwang of Hankook APT 214-806, Youngtong-Dong, Paldal-Ku Suwon-City, Kyungki-Do, Republic of Korea, Hong-Sik Jeong of LG-Samick APT 112-204, Homsesil-Dong, Kyonsin-Ku, Suwon-City, Kyungki-Do, Republic of Korea, and Ki-Nam Kim of Kummaent Life APT 108-507, Pyunghon-Dong, Dangan-Ku, Anyang-City, Kyungki-Do, Republic of Korea, having invented improvements in **BIT LINE LANDING PAD AND BORDERLESS CONTACT ON BIT LINE STUD WITH LOCALIZED ETCH STOP LAYER AND MANUFACTURING METHOD THEREOF** described in an application for Letters Patent of the United States, executed by us on even date herewith, for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignee, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

First or Sole Inventor:

Signature:

Won-Suk Yang
Won-Suk Yang

Date: October 21, 2000

Second Joint Inventor:

Signature:

Yoo-Sang Hwang
Yoo-Sang Hwang

Date: October 26, 2000

Third Joint Inventor:

Signature:

Hong-Sik Jeong
Hong-Sik Jeong

Date: October 26, 2000

Fourth Joint Inventor:

Signature:

Ki-Nam Kim
Ki-Nam Kim

Date: October 26, 2000

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